

2SJ0672

Silicon P-channel MOSFET

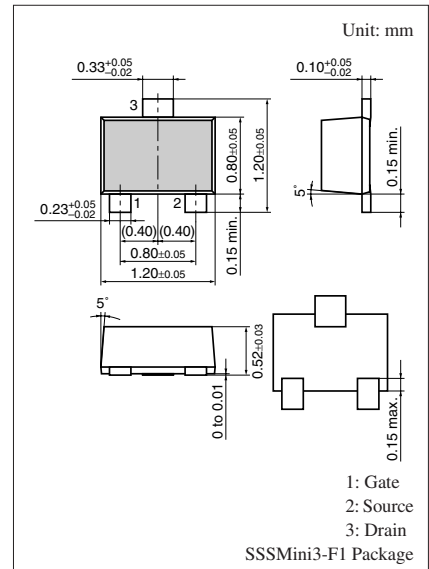
For switching circuits

■ Features

- Ultra small package switching MOSFETs
- SSS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing.

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Drain-source voltage	V_{DS}	-30	V
Gate-source voltage (Drain open)	V_{GSO}	± 7	V
Drain current	I_D	-100	mA
Peak drain current	I_{DP}	-200	mA
Power dissipation	P_D	100	mW
Channel temperature	T_{ch}	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$



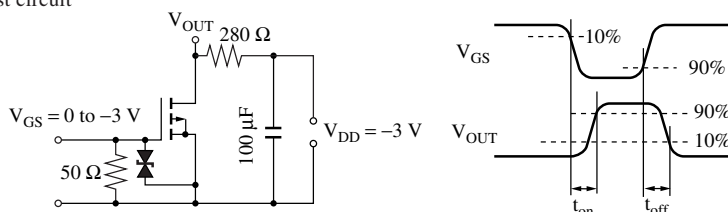
Marking Symbol: 5M

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-source surrender voltage	V_{DSS}	$I_D = -10 \mu\text{A}$, $V_{GS} = 0$	-30			V
Drain-source cutoff current	I_{DSS}	$V_{DS} = -20 \text{ V}$, $V_{GS} = 0$			-0.1	μA
Gate-source cutoff current	I_{GSS}	$V_{GS} = \pm 7 \text{ V}$, $V_{DS} = 0$			± 10	μA
Gate threshold voltage	V_{th}	$V_{DS} = -3.0 \text{ V}$, $I_D = -1.0 \mu\text{A}$	-0.5	-1.0	-1.5	V
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = 3 \text{ V}$, $I_D = 10 \text{ mA}$, $f = 1 \text{ kHz}$	20	35		mS
Drain-source ON resistance	$R_{DS(on)}$	$V_{GS} = -2.5 \text{ V}$, $I_D = -10 \text{ mA}$		20	45	Ω
		$V_{GS} = -4.0 \text{ V}$, $I_D = -10 \text{ mA}$		15	30	
Short-circuit forward transfer capacitance (Common source)	C_{iss}	$V_{DS} = -3 \text{ V}$, $V_{GS} = 0$, $f = 1 \text{ MHz}$		10		pF
Short-circuit output capacitance (Common source)	C_{oss}			7		
Reverse transfer capacitance (Common source)	C_{rss}			3		
Turn-on time *	t_{on}	$V_{DD} = -3 \text{ V}$, $V_{GS} = 0 \text{ V} \sim -3 \text{ V}$ $I_D = -10 \text{ mA}$		850		ns
Turn-off time *	t_{off}	$V_{DD} = -3 \text{ V}$, $V_{GS} = -3 \text{ V} \sim 0 \text{ V}$ $I_D = -10 \text{ mA}$		850		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: t_{on} , t_{off} test circuit



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